

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	IC1,IC2	2	—	TPD7104AF	TOSHIBA		PS8	2.9 x 2.8
2	IC3	1	—	LTC6101BCS5	Analog Devices		TSOT-23	2.9 x 2.8
3	Q1,Q2	2	—	TKR74F04PB	TOSHIBA	Power MOS FET	TO220-SM(W)	10 x 13
4	D1,D2,D3,D4	4	—	CRZ16	TOSHIBA	Zener Diode	S-FLAT	1.6 x 3.5
5	D5	1	—	CMG07	TOSHIBA	Diode	M-FLAT	2.4 x 4.7
6	D6,D7	2	—	CMZ27	TOSHIBA	Zener Diode	M-FLAT	2.4 x 4.7
7	D8,D9,D10	3	—	1SS352	TOSHIBA	Diode	USC	2.5 x 1.25
8	R1	1	0.5mΩ	PSJ2NTEBL500F BVS-M-R0005-1.0	KOA Isabellenhutte	10W,±1% 9W,±1%	-	10 x 5.2
9	R2	1	300Ω			63mW,±1%		1.6 x 0.8 (0603)
10	R3,R5	2	10kΩ			63mW,±5%		1.6 x 0.8 (0603)
11	R4	1	10kΩ			63mW,±1%		1.6 x 0.8 (0603)
12	R6,R7,R8,R9	4	10kΩ			63mW,±5%		1.6 x 0.8 (0603)
13	R10,R11	2	20kΩ			63mW,±5%		1.6 x 0.8 (0603)
14	R12	1	1kΩ			63mW,±5%		1.6 x 0.8 (0603)
15	C1,C2,C3	3	1μF			Ceramic, 25V, ±10%		1.6 x 0.8 (0603)
16	C4,C5	2	10nF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
17	C6	1	100nF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
18	C7	1	15pF			Ceramic, 50V, ±5%		1.6 x 0.8 (0603)

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